

SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

03.04.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	337		2		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		3		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		4		
		70	L2			
C-RaS-FR4-DS-2.388mm-070+070-TG150-HF...	50203158	2248		5	A00	B00
		70	L3			
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	337		6		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		7		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		8		
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	9		

Thickness after Pressing

B00:

3090 µm

Tol+:

320 µm

Tol-:

320 µm

Dmax:

3410 µm

Dmin:

2770 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

3200 µm

Tol+:

320 µm

Tol-:

320 µm

Dmax:

3520 µm

Dmin:

2880 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

3132 µm

Version 1.2.20.35

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